IPC ASSOCIATION ELECTRONIC	© Copyright 2005.	Material Composition Declaration © Copyright 2005. IPC, Bannockburn, Illinois. All rights international and Pan-American copyright conventions.		All rights reserved unontions.	der both	both This document is a level parts, the dea		is a declaration of the substances within the manufacturer listed item. Note: if the item is an assembly with lowed declaration encompasses all lower level materials for which the manufacturer has engineering responsibility.						
752-21.1	.1 IPC Web Site for Information on IPC-1752 Standard Form Typhttp://www.ipc.org/IPC-175x Distribute								ials and M	ials and Mfg Information				
Supplier	r Information													
Company name*				Company unique ID			Unique ID Authority				Response Date*			
onsemi											2025-08-03			
Contact N	ame		Title - Contact			1	Phone - Contact*				Email - Contact*			
Product-I	Env-Stewards		Product Enviro Compliance				NA				Product-Env-Stewards@onsemi.com			
uthorize	d Representative*		Title - Representative			I	Phone - Representative*				Email - Representative*			
Product-I	Env-Stewards		Product Enviro Compliance				NA				Product-Env-Stewards@onsemi.com			
	Requester Item Number Mfr Iter		n Number Mfr Item Name				Effective Da	Effective Date Version Manufacturing S		Manufacturing Site		Weight*	UOM	Unit Type
		FDWS86380-F085 NMOS PWR56		NMOS PWR56 80	V 13 mOhm	Ohm 2025-0				РВВ		161.1927	mg	Each
Manufa	cturing Process Inform													
2				ninal Base Alloy J-STD-020 MSL Rat		SL Rating				ature Max Time at Peak Tempe		ture Numb	er of Reflow Cy	cles
	Matte Tin (Sn) - annealed	C	U Alloy	1			260		C	30	secor	ids 3		
Comments														
vel 1 - m	aximum time at peak tempera	ture during sol	dering is 10-3	30 seconds										
or more	information regarding materia	l composition	please refer to	page 3										

RoHS Material Composition Declaration			Declaration Type *	Detailed						
Directive 2015/863/EU amending RoHS Directive 2011/65/EU RoHS Definition: Quantity limit of 0.01% by mass (100 PPM) in homogeneous material for Cadmium and quantity limit of 0.1% by mass (1000 PPM) in homogeneous material for: Lead (Pb), Mercury (Hg), Hexavalent Chromium (Cr6+), Polybrominated Biphenyls (PBB), Polybrominated Diphenyl Ethers (PBDE), and Bis(2-ethylhexyl) phthalate (DEHP), Benzyl-butyl phthalate (BBP), Dibutyl phthalate (DBP), Diisobutyl phthalate (DIBP).										
Please indicate whether any homogeneous material (as defined by the RoHS Directive, EU 2011/65/EU and implemented by the laws of the European Union member states) of the part identified on this form contains lead, mercury, cadmium, hexavalentchromium, polybrominated biphenyls and/or polybrominated diphenyl ethers (each a "RoHS restricted substance") in excess of the applicable quantity limit identified above. If a homogeneous material within the part contains a RoHS restricted substance inexcess of an applicable quantity limit, please indicate below which, if any, RoHS exemption you believe may apply. If the part is an assembly with lower level components, the declaration shall encompass all such components. Supplier certifies that it gathered the information it provides in this form using appropriate methods to ensure its accuracy and that such information is true and correct to the best of its knowledges and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products with European Union member state laws that implement the RoHS Directive. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its paragraph. If the Company and the Supplier supplier have provided certifications regarding their contributions to the part, and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part, the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusivesource of the Supplier's Standard Terms and Conditions of Sale applicable to suc										
RoHS Declaration * 4 - Item(s) does not contain RoHS restricted substance	s per the definition above except for selected exemp	tions Supplier Acceptance	* Accepted						
Exemption: 7a: Lead in high melting temperature type solders (i.e. lead based solder alloys containing 85% by weight or more lead).										
Exemption List Version	EL-2011/534/EU									
Declaration Signature										
Instructions: Complete all of the required f Requester) and click on Submit Form to ha		Accepted" on the Supplier Acceptance drop-dow	n. This will display the signature area. Digita	lly sign the declaration (if required by the						
Supplier Digital Signature Ra	astislav Drska	-En								

Homogeneous Material Composition Declaration for Electronic Products

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

Substance Instructions: [A] select the Level (JIG A, JIG B, Requester or Supplier) [B] select the substance category (JIG or Requester) or enter a value (Supplier). [C] select the substance (JIG) or enter the substance and CAS (Other). [D] select a RoHS exemption, if applicable [E] enter the weight of the substance or the PPM concentration [F] Optionally enter the positive (+) and negative (-) tolerance in percent (Note: percent tolerance values are expected to cover a 3 sigma range of distribution unless otherwise noted).

Homogeneous Material	Weight	Unit of Measure	Level	Substance	CAS	Exempt	Weight	Unit of Measure
Die	4.8845	mg	Supplier	Silicon (Si)	7440-21-3		4.8845	mg
Die Attach Solder	4.5182	mg	Supplier	Silver (Ag)	7440-22-4		0.113	mg
			A	Lead (Pb)	7439-92-1	7a	4.1793	mg
			Supplier	Tin (Sn)	7440-31-5		0.2259	mg
Lead Frame	55.839	mg	Supplier	Zinc (Zn)	7440-66-6		0.0223	mg
			В	Nickel (Ni)	7440-02-0		0.6701	mg
			Supplier	Iron (Fe)	7439-89-6		1.4741	mg
			Supplier	Copper (Cu)	7440-50-8		53.6669	mg
			Supplier	Phosphorus (P)	7723-14-0		0.0056	mg
Mold Compound-Black	72.7	mg		Epoxy resin	proprietary data		9.6691	mg
			Supplier	Carbon Black (C)	1333-86-4		0.1454	mg
			Supplier	Fused Silica (SiO2)	60676-86-0		62.8855	mg
Plating	16.979	mg	Supplier	Tin (Sn)	7440-31-5		16.979	mg
Wire Bond - Al	6.272	mg	В	Nickel (Ni)	7440-02-0		0.0003	mg
		_	Supplier	Aluminum (Al)	7429-90-5		6.2717	mg